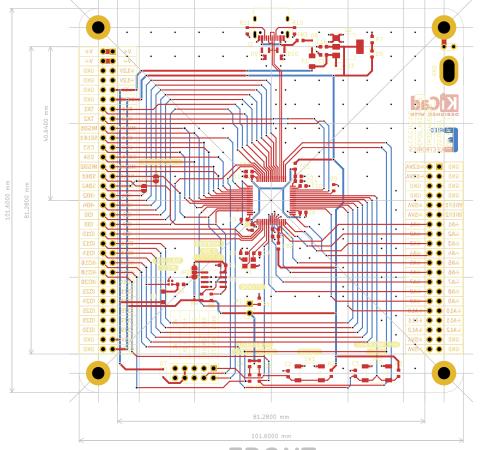
BACK



BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.6062 mm

Board overall dimensions: 101.6000 mm x 101.6000 mm

Min track/spacing: 0.2000 mm / 0.2000 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes
Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	
F.Paste	Top Solder Paste		0 mm		1	
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	
F.Cu	copper		0.035 mm		1	
Dielectric 1	prepreg	JLC7628	0.2104 mm		4.6	0.02
GND1.Cu	copper		0.0152 mm		1	
Dielectric 2	core	FR4	1.065 mm		4.6	0.02
GND2.Cu	copper		0.0152 mm		1	
Dielectric 3	prepreg	JLC7628	0.2104 mm		4.6	0.02
B.Cu	copper		0.035 mm		1	
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	
B.Paste	Bottom Solder Paste		0 mm		1	
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	

FRONT

Sheet:

File: STM32F405RGT6.kicad_pcb

Title: STM32F405RGT6

 Size: A4
 Date: 2022-08-30
 Rev: V22.08.0.1

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